

LM185-1.2-N/LM285-1.2-N/LM385-1.2-N Micropower Voltage Reference Diode

 Check for Samples: [LM185-1.2-N](#), [LM285-1.2-N](#), [LM385-1.2-N](#)

FEATURES

- $\pm 1\%$ and 2% Initial Tolerance
- Operating Current of $10\mu\text{A}$ to 20mA
- 1Ω Dynamic Impedance
- Low Temperature Coefficient
- Low Voltage Reference— 1.235V
- 2.5V Device and Adjustable Device Also Available
- LM185-2.5 Series and LM185 Series, respectively

DESCRIPTION

The LM185-1.2-N/LM285-1.2-N/LM385-1.2-N are micropower 2-terminal band-gap voltage regulator diodes. Operating over a $10\mu\text{A}$ to 20mA current range, they feature exceptionally low dynamic impedance and good temperature stability. On-chip trimming is used to provide tight voltage tolerance. Since the LM185-1.2-N band-gap reference uses only transistors and resistors, low noise and good long term stability result.

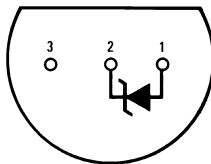
Careful design of the LM185-1.2-N has made the device exceptionally tolerant of capacitive loading, making it easy to use in almost any reference application. The wide dynamic operating range allows its use with widely varying supplies with excellent regulation.

The extremely low power drain of the LM185-1.2-N makes it useful for micropower circuitry. This voltage reference can be used to make portable meters, regulators or general purpose analog circuitry with battery life approaching shelf life.

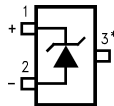
Further, the wide operating current allows it to replace older references with a tighter tolerance part.

The LM185-1.2-N is rated for operation over a -55°C to 125°C temperature range while the LM285-1.2-N is rated -40°C to 85°C and the LM385-1.2-N 0°C to 70°C . The LM185-1.2-N/LM285-1.2-N are available in a hermetic TO package and the LM285-1.2-N/LM385-1.2-N are also available in a low-cost TO-92 molded package, as well as SOIC and SOT-23.

CONNECTION DIAGRAM



**Figure 1. T0-92 Package (LP)
(Bottom View)**



* Pin 3 is attached to the Die Attach Pad (DAP) and should be connected to Pin 2 or left floating.

Figure 2. SOT-23

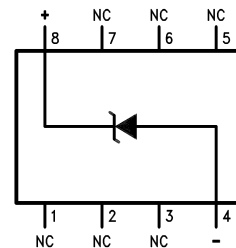
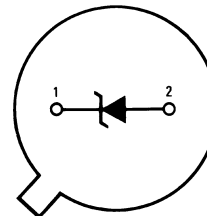


Figure 3. SOIC Package



**Figure 4. TO Package (NDV)
(Bottom View)**



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾⁽²⁾⁽³⁾

Reverse Current	30mA
Forward Current	10mA
Operating Temperature Range ⁽⁴⁾	
LM185-1.2-N	-55°C to +125°C
LM285-1.2-N	-40°C to +85°C
LM385-1.2-N	0°C to 70°C
ESD Susceptibility ⁽⁵⁾	2kV
Storage Temperature	-55°C to +150°C
Soldering Information	
TO-92 package: 10 sec.	260°C
TO package:10 sec.	300°C
SOIC and SOT-23 Pkg.	
Vapor phase (60 sec.)	215°C
Infrared (15 sec.)	220°C
See AN-450 "Surface Mounting Methods and Their Effect on Product Reliability" for other methods of soldering surface mount devices.	

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional. For specifications and test conditions, see the Electrical Characteristics. The specifications apply only for the test conditions listed.
- (2) Refer to RETS185H-1.2 for military specifications.
- (3) If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.
- (4) For elevated temperature operation, see [Table 1](#).
- (5) The human body model is a 100 pF capacitor discharged through a 1.5 kΩ resistor into each pin.

Table 1. $T_{J(max)}$ for Elevated Temperature Operation

DEVICE	$T_{J(max)}$ (°C)
LM185-1.2-N	150
LM285-1.2-N	125
LM385-1.2-N	100

ELECTRICAL CHARACTERISTICS⁽¹⁾

Parameter	Conditions	Typ	LM185-1.2-N LM185BX-1.2-N LM185BY-1.2-N LM285-1.2-N LM285BX-1.2-N LM285BY-1.2-N		LM385B-1.2-N LM385BX-1.2-N LM385BY-1.2-N		LM385-1.2-N		Units (Limit)
			Tested Limit ⁽³⁾	Design Limit ⁽⁴⁾	Tested Limit ⁽²⁾	Design Limit ⁽⁴⁾	Tested Limit ⁽²⁾	Design Limit ⁽⁴⁾	
Reverse Breakdown Voltage	$T_A = 25^\circ\text{C}$, $10\mu\text{A} \leq I_R \leq 20\text{mA}$	1.23 5	1.223		1.223		1.205		V(Min)
			1.247		1.247		1.260		V(Max)
Minimum Operating Current		8	10	20	15	20	15	20	μA
	LM385M3-1.2-N						10	15	(Max)
Reverse Breakdown Voltage Change with Current	$10\mu\text{A} \leq I_R \leq 1\text{mA}$		1	1.5	1	1.5	1	1.5	mV (Max)
	$1\text{mA} \leq I_R \leq 20\text{mA}$		10	20	20	25	20	25	mV (Max)
Reverse Dynamic Impedance	$I_R = 100\mu\text{A}$, $f = 20\text{Hz}$	1							Ω
Wideband Noise (rms)	$I_R = 100\mu\text{A}$, $10\text{Hz} \leq f \leq 10\text{kHz}$	60							μV
Long Term Stability	$I_R = 100\mu\text{A}$, $T = 1000\text{ Hr}$, $T_A = 25^\circ\text{C} \pm 0.1^\circ\text{C}$	20							ppm
Average Temperature Coefficient ⁽⁵⁾	$I_R = 100\mu\text{A}$ X Suffix Y Suffix All Others		30 50		30 50			150	ppm/ $^\circ\text{C}$ ppm/ $^\circ\text{C}$ ppm/ $^\circ\text{C}$ (Max)

(1) Parameters identified with boldface type apply at temperature extremes. All other numbers apply at $T_A = T_J = 25^\circ\text{C}$.

(2) Production tested.

(3) A military RETS electrical specification is available on request.

(4) Specified by design. Not production tested. These limits are not used to calculate average outgoing quality levels.

(5) The average temperature coefficient is defined as the maximum deviation of reference voltage at all measured temperatures between the operating T_{MAX} and T_{MIN} , divided by $T_{\text{MAX}} - T_{\text{MIN}}$. The measured temperatures are -55°C , -40°C , 0°C , 25°C , 70°C , 85°C , 125°C .

THERMAL CHARACTERISTICS

Thermal Resistance	TO-92	TO	SOIC	SOT-23
θ_{JA} (junction to ambient)	180 $^\circ\text{C}/\text{W}$ (0.4" leads) 170 $^\circ\text{C}/\text{W}$ (0.125" leads)	440 $^\circ\text{C}/\text{W}$	165 $^\circ\text{C}/\text{W}$	283 $^\circ\text{C}/\text{W}$
θ_{JC} (junction to case)	N/A	80 $^\circ\text{C}/\text{W}$	N/A	N/A

TYPICAL PERFORMANCE CHARACTERISTICS

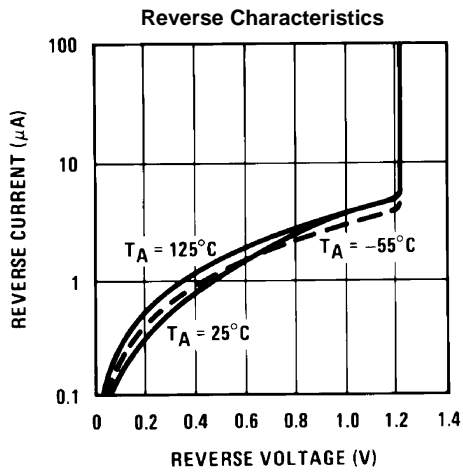


Figure 5.

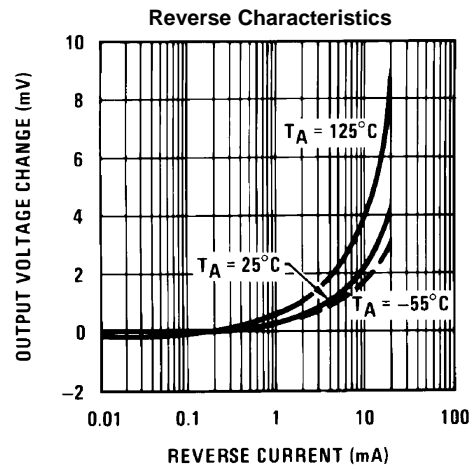


Figure 6.

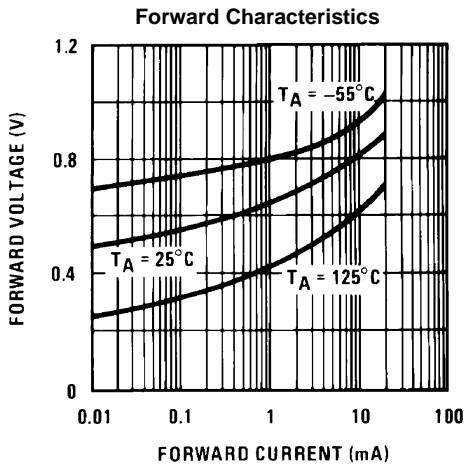


Figure 7.

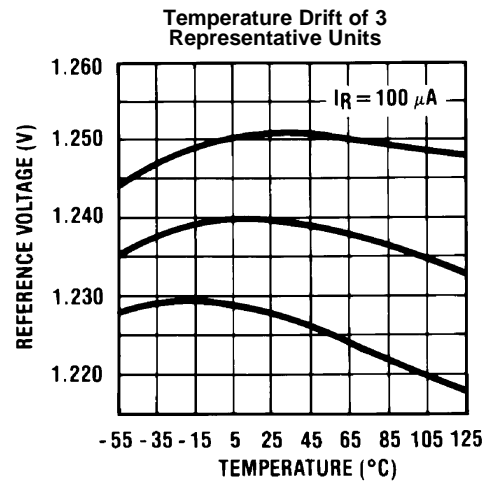


Figure 8.

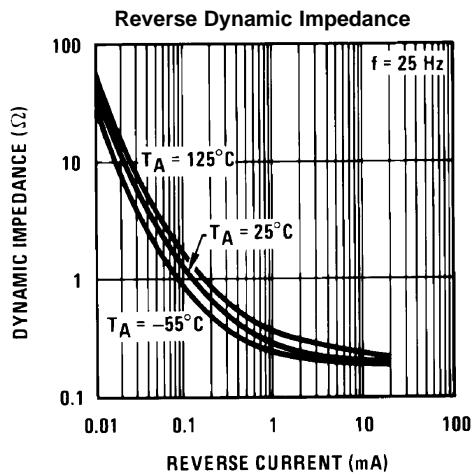


Figure 9.

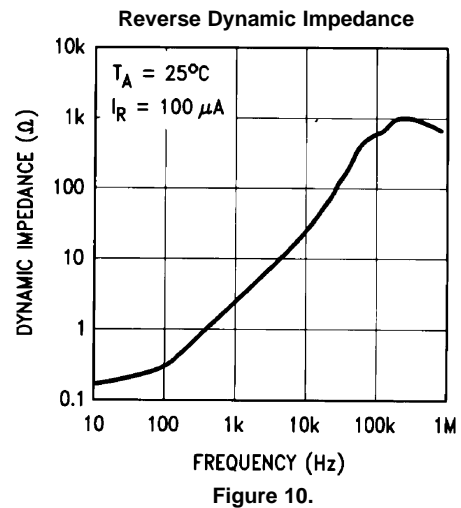


Figure 10.

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

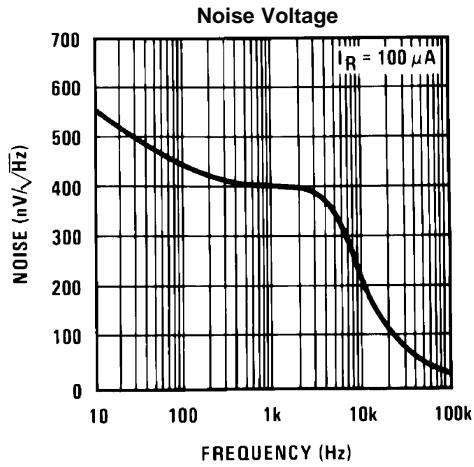


Figure 11.

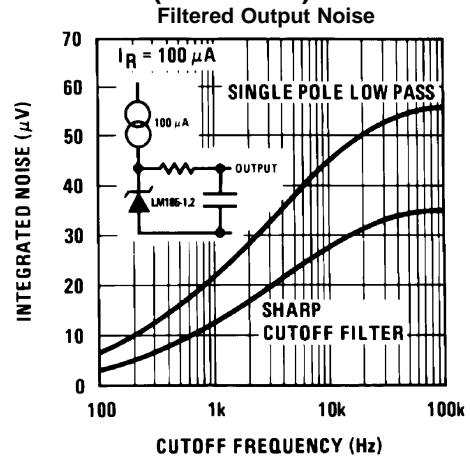


Figure 12.

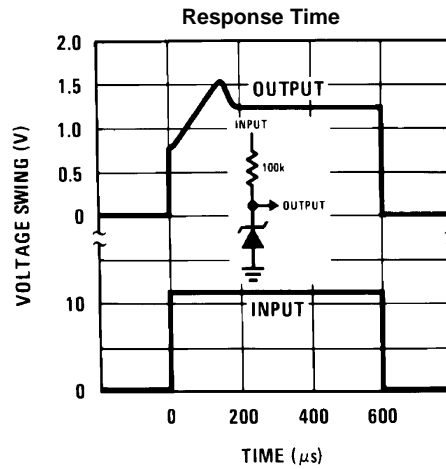


Figure 13.

TYPICAL APPLICATIONS

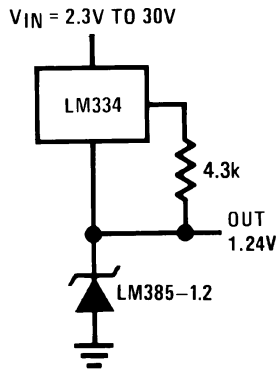


Figure 14. Wide Input Range Reference

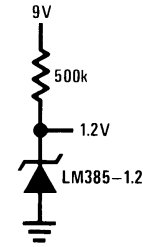


Figure 15. Micropower Reference from 9V Battery

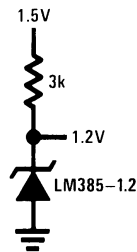
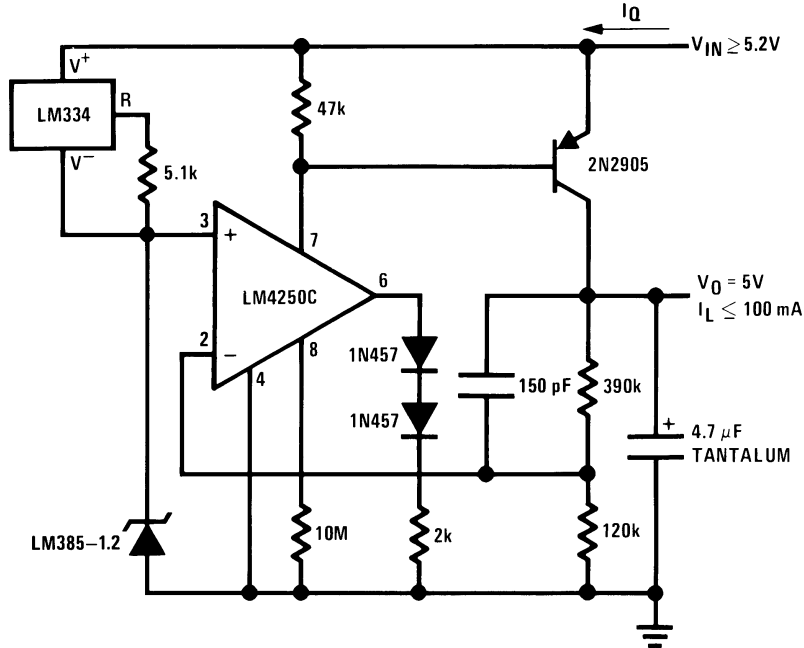
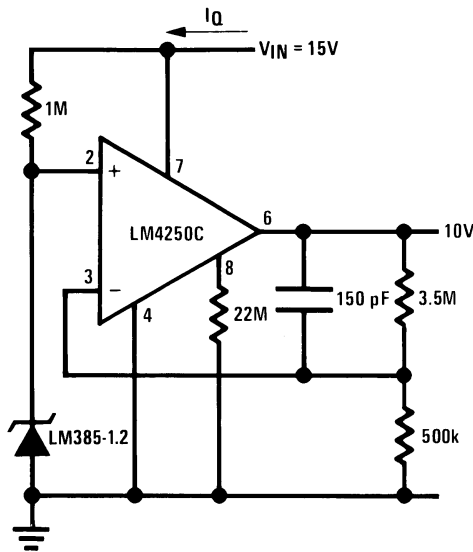


Figure 16. Reference from 1.5V Battery



* $I_Q \approx 30\mu A$

Figure 17. Micropower* 5V Regulator



* $I_Q \approx 20\mu\text{A}$ standby current

Figure 18. Micropower* 10V Reference

$$*I_{OUT} = \frac{1.23V}{R2}$$

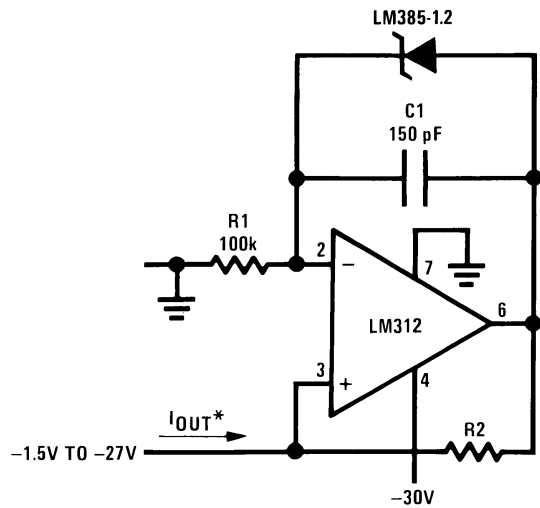


Figure 19.

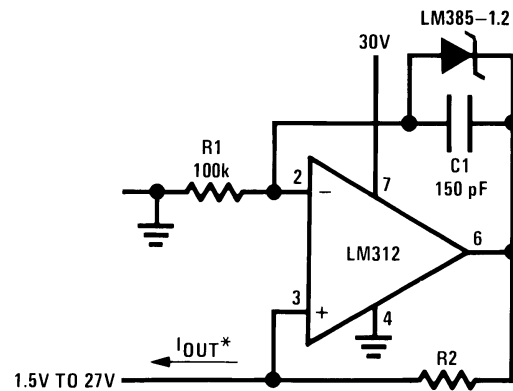
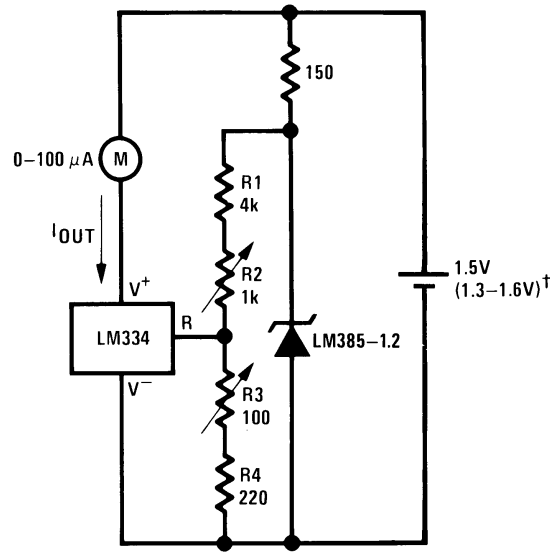


Figure 20. Precision 1µA to 1mA Current Sources

METER THERMOMETERS

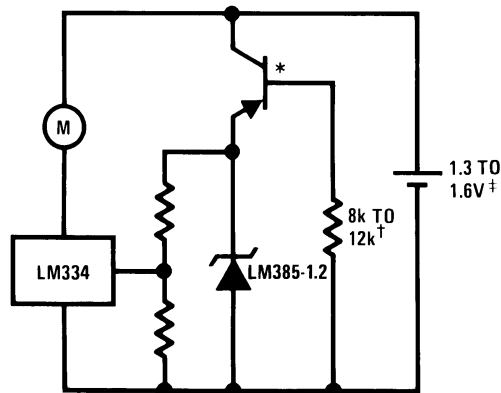


Calibration

1. Short LM385-1.2-N, adjust R3 for $I_{OUT} = \text{temp}$ at $1\mu\text{A}/^\circ\text{K}$
 2. Remove short, adjust R2 for correct reading in centigrade
- † I_Q at 1.3V = $500\mu\text{A}$
 I_Q at 1.6V = 2.4mA

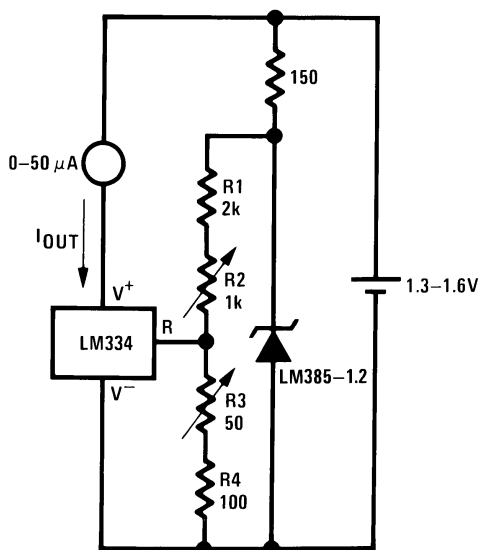
Figure 21. 0°C–100°C Thermometer

Figure 22.



- *2N3638 or 2N2907 select for inverse $H_{FE} \approx 5$
 †Select for operation at 1.3V
 ‡ $I_Q \approx 600\mu\text{A}$ to $900\mu\text{A}$

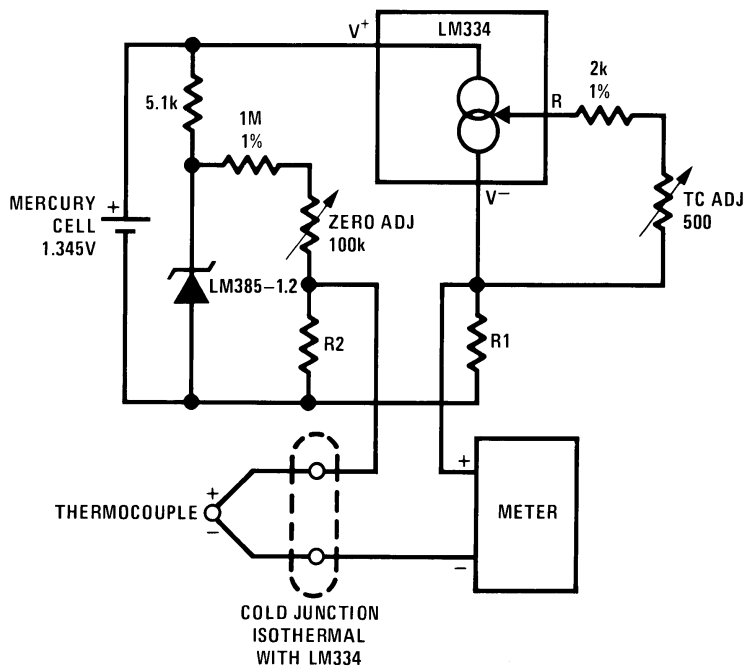
Figure 23. Lower Power Thermometer



Calibration

1. Short LM385-1.2-N, adjust R3 for $I_{OUT} = \text{temp at } 1.8\mu\text{A}/^\circ\text{K}$
2. Remove short, adjust R2 for correct reading in $^\circ\text{F}$

Figure 24. 0°F–50°F Thermometer



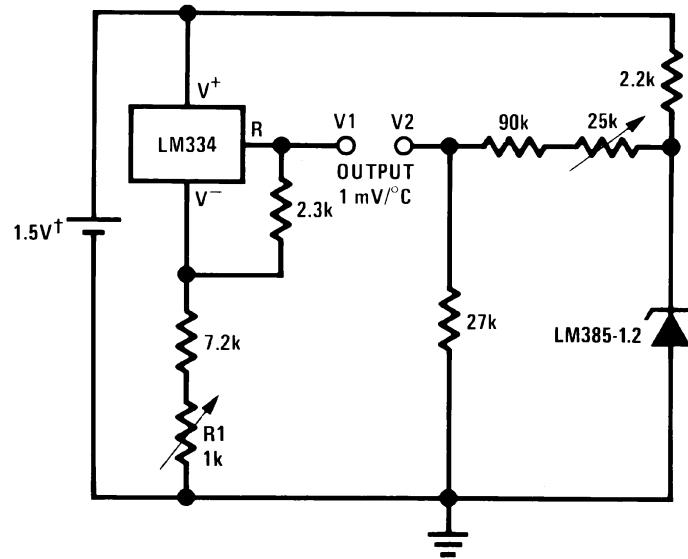
Adjustment Procedure

1. Adjust TC ADJ pot until voltage across R1 equals Kelvin temperature multiplied by the thermocouple Seebeck coefficient.
2. Adjust zero ADJ pot until voltage across R2 equals the thermocouple Seebeck coefficient multiplied by 273.2.

Figure 25. Micropower Thermocouple Cold Junction Compensator

Thermocouple Type	Seebeck Coefficient ($\mu\text{V}/^\circ\text{C}$)	R1 (Ω)	R2 (Ω)	Voltage Across R1 @ 25°C (mV)	Voltage Across R2 (mV)
J	52.3	523	1.24k	15.60	14.32
T	42.8	432	1k	12.77	11.78
K	40.8	412	953 Ω	12.17	11.17
S	6.4	63.4	150 Ω	1.908	1.766

Typical supply current 50 μA

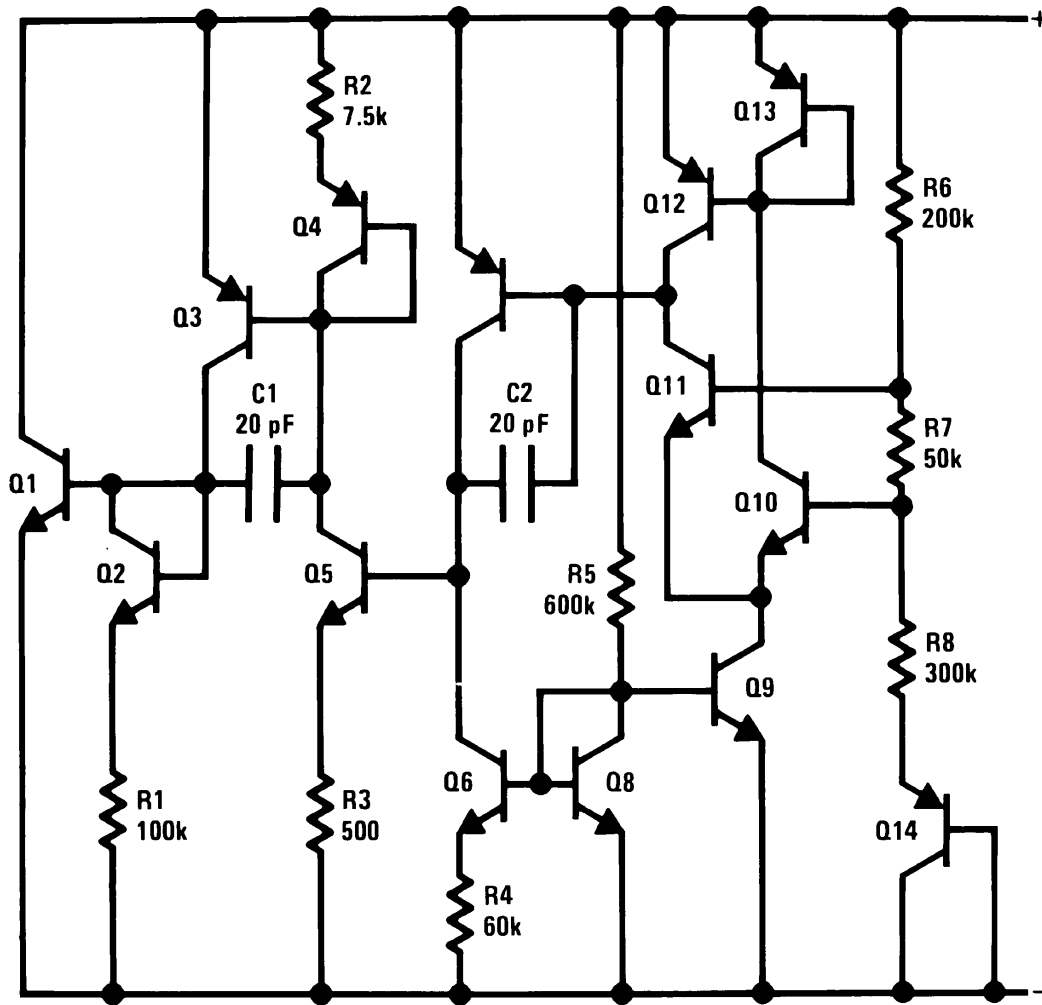


Calibration

1. Adjust R1 so that V1 = temp at 1mV/°K
 2. Adjust V2 to 273.2mV
- †I_Q for 1.3V to 1.6V battery voltage = 50 μA to 150 μA

Figure 26. Centigrade Thermometer

SCHEMATIC DIAGRAM



REVISION HISTORY

Changes from Revision D (April 2013) to Revision E	Page
• Changed layout of National Data Sheet to TI format	11

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LM185BYH-1.2	ACTIVE	TO	NDU	2	1000	TBD	Call TI	Call TI	-55 to 125	LM185BYH1.2	Samples
LM185BYH-1.2/NOPB	ACTIVE	TO	NDU	2	1000	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	-55 to 125	LM185BYH1.2	Samples
LM185H-1.2	ACTIVE	TO	NDU	2	1000	TBD	Call TI	Call TI	-55 to 125	LM185H1.2	Samples
LM185H-1.2/NOPB	ACTIVE	TO	NDU	2	1000	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	-55 to 125	LM185H1.2	Samples
LM285BXM-1.2/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	285BX M1.2	Samples
LM285BXM-1.2/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	285BX M1.2	Samples
LM285BXZ-1.2/LFT4	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM		285BX Z-1.2	Samples
LM285BXZ-1.2/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM	-40 to 85	285BX Z-1.2	Samples
LM285BYM-1.2/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	285BY M1.2	Samples
LM285BYM-1.2/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	285BY M1.2	Samples
LM285H-1.2	ACTIVE	TO	NDU	2	1000	TBD	Call TI	Call TI	-40 to 85	LM285H1.2	Samples
LM285H-1.2/NOPB	ACTIVE	TO	NDU	2	1000	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	-40 to 85	LM285H1.2	Samples
LM285M-1.2/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM285 M1.2	Samples
LM285M-1.2/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM285 M1.2	Samples
LM285Z-1.2/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM	-40 to 85	LM28 5Z-1.2	Samples
LM385BM-1.2	ACTIVE	SOIC	D	8	95	TBD	Call TI	Call TI	0 to 70	LM385 BM1.2	Samples
LM385BM-1.2/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM385 BM1.2	Samples
LM385BMX-1.2	ACTIVE	SOIC	D	8	2500	TBD	Call TI	Call TI	0 to 70	LM385	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
										BM1.2	
LM385BMX-1.2/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM385 BM1.2	Samples
LM385BXM-1.2/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	385BX M1.2	Samples
LM385BXM-1.2/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	385BX M1.2	Samples
LM385BXZ-1.2/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM	0 to 70	385BX Z-1.2	Samples
LM385BYM-1.2/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	385BY M1.2	Samples
LM385BYMX-1.2	ACTIVE	SOIC	D	8	2500	TBD	Call TI	Call TI	0 to 70	385BY M1.2	Samples
LM385BYMX-1.2/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	385BY M1.2	Samples
LM385BYZ-1.2/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM	0 to 70	385BY Z-1.2	Samples
LM385BZ-1.2/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM	0 to 70	LM385 BZ1.2	Samples
LM385M-1.2	ACTIVE	SOIC	D	8	95	TBD	Call TI	Call TI	0 to 70	LM385 M1.2	Samples
LM385M-1.2/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM385 M1.2	Samples
LM385M3-1.2	ACTIVE	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	0 to 70	R11	Samples
LM385M3-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	R11	Samples
LM385M3X-1.2	ACTIVE	SOT-23	DBZ	3	3000	TBD	Call TI	Call TI	0 to 70	R11	Samples
LM385M3X-1.2/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	R11	Samples
LM385MX-1.2	ACTIVE	SOIC	D	8	2500	TBD	Call TI	Call TI	0 to 70	LM385 M1.2	Samples
LM385MX-1.2/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM385 M1.2	Samples
LM385Z-1.2/LFT3	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM		LM385 Z-1.2	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LM385Z-1.2/LFT4	ACTIVE	TO-92	LP	3	2000	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM		LM385 Z-1.2	Samples
LM385Z-1.2/NOPB	ACTIVE	TO-92	LP	3	1800	Green (RoHS & no Sb/Br)	SNCU	Level-1-NA-UNLIM	0 to 70	LM385 Z-1.2	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

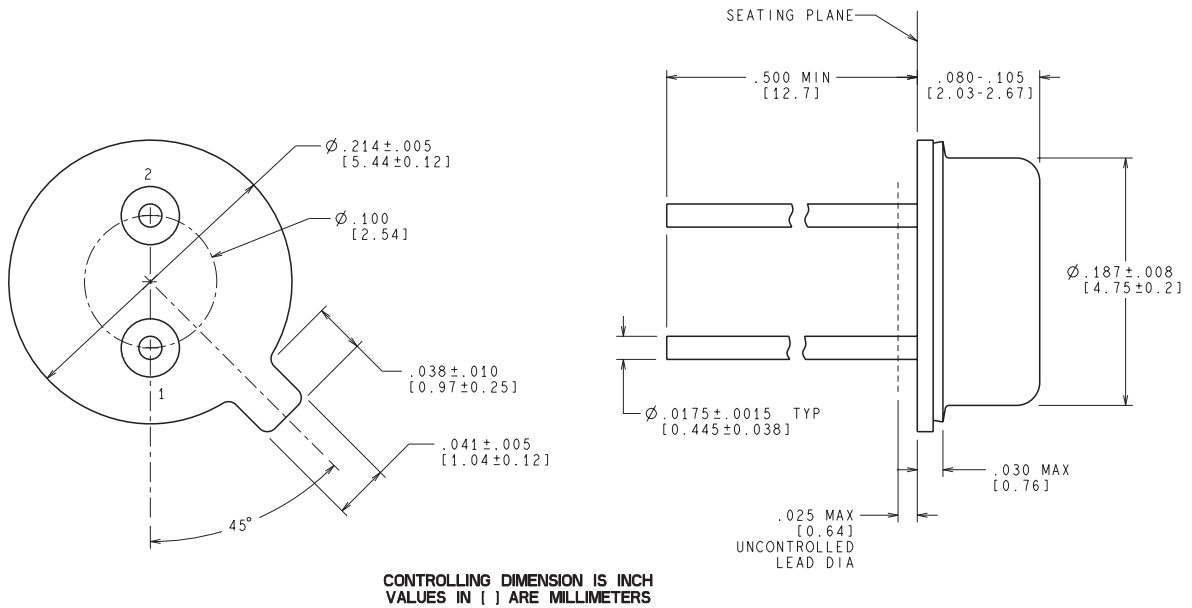
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM285BXM-1.2/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM285BYM-1.2/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM285M-1.2/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385BM-1.2	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385BM-1.2/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385BXM-1.2/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385BYM-1.2	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385BYM-1.2/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385M3-1.2	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM385M3-1.2/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM385M3X-1.2	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM385M3X-1.2/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM385M-1.2	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM385M-1.2/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM285BXM3-1.2/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM285BYMX-1.2/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM285MX-1.2/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM385BM3-1.2	SOIC	D	8	2500	367.0	367.0	35.0
LM385BM3-1.2/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM385BXM3-1.2/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM385BYMX-1.2	SOIC	D	8	2500	367.0	367.0	35.0
LM385BYMX-1.2/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM385M3-1.2	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM385M3-1.2/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM385M3X-1.2	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM385M3X-1.2/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM385MX-1.2	SOIC	D	8	2500	367.0	367.0	35.0
LM385MX-1.2/NOPB	SOIC	D	8	2500	367.0	367.0	35.0

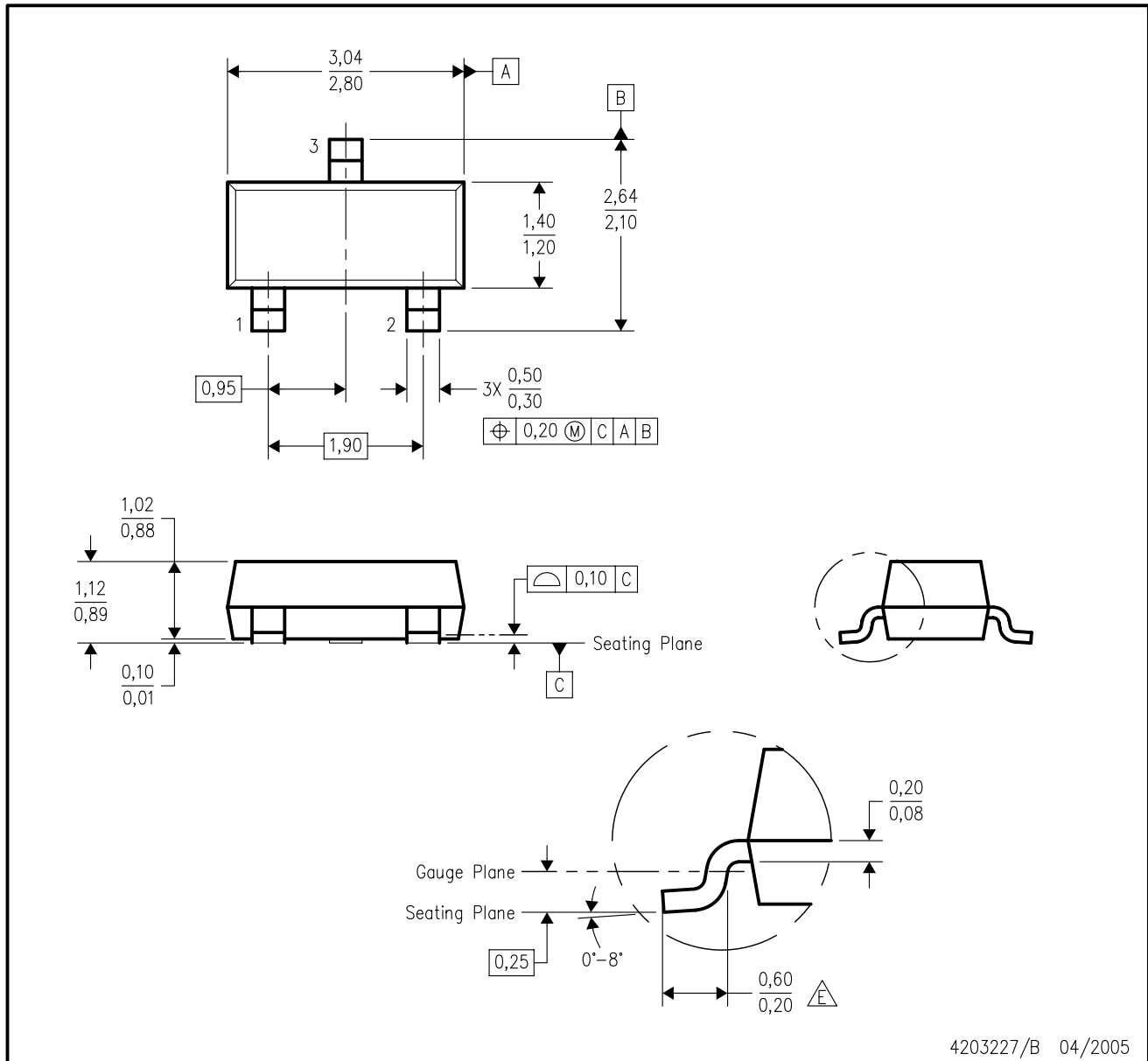
NDU0002A



H02A (Rev F)

DBZ (R-PDSO-G3)

PLASTIC SMALL-OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Lead dimensions are inclusive of plating.
 - D. Body dimensions are exclusive of mold flash and protrusion. Mold flash and protrusion not to exceed 0.25 per side.
 - $\triangle E$ Falls within JEDEC TO-236 variation AB, except minimum foot length.

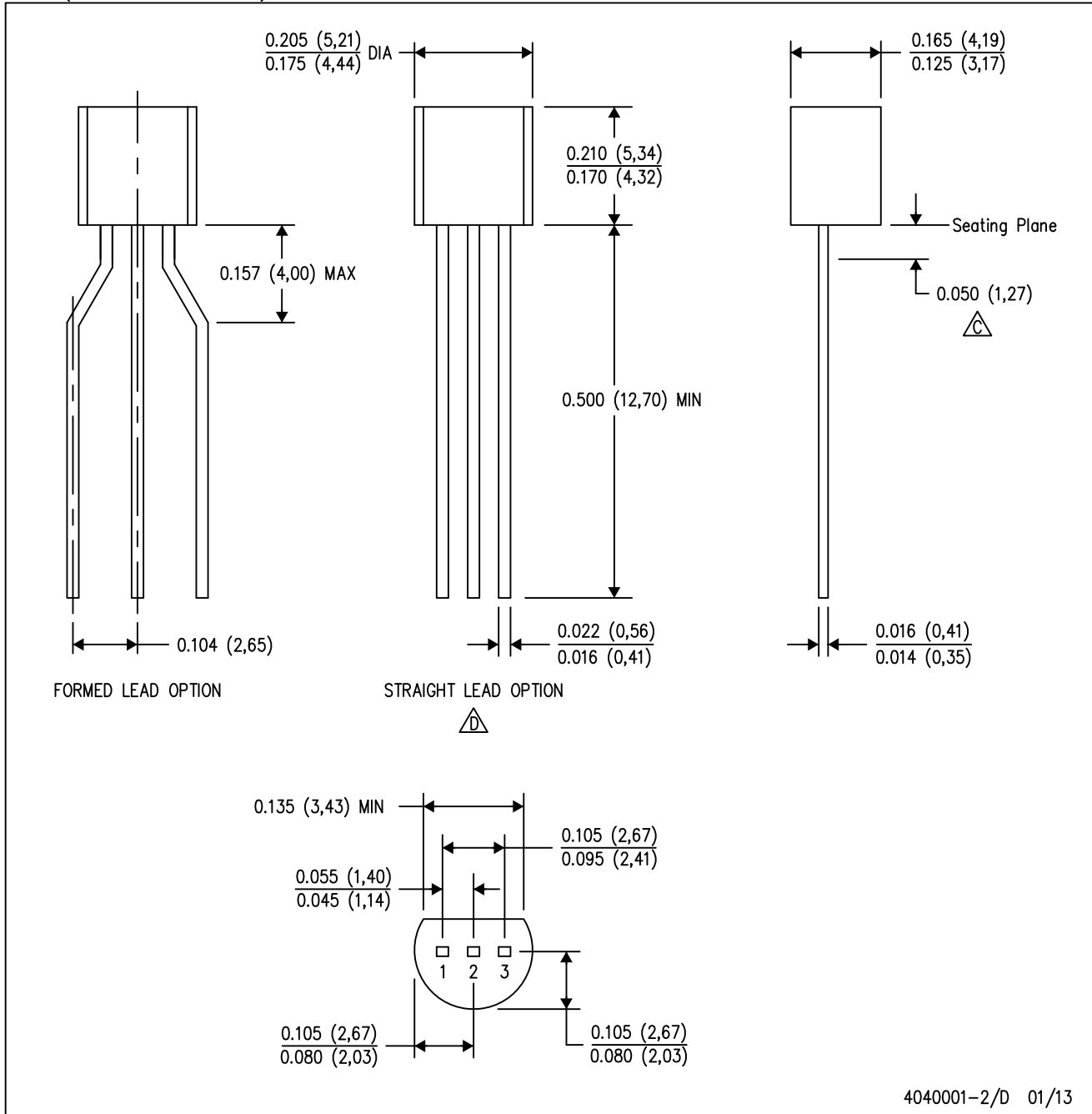
D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



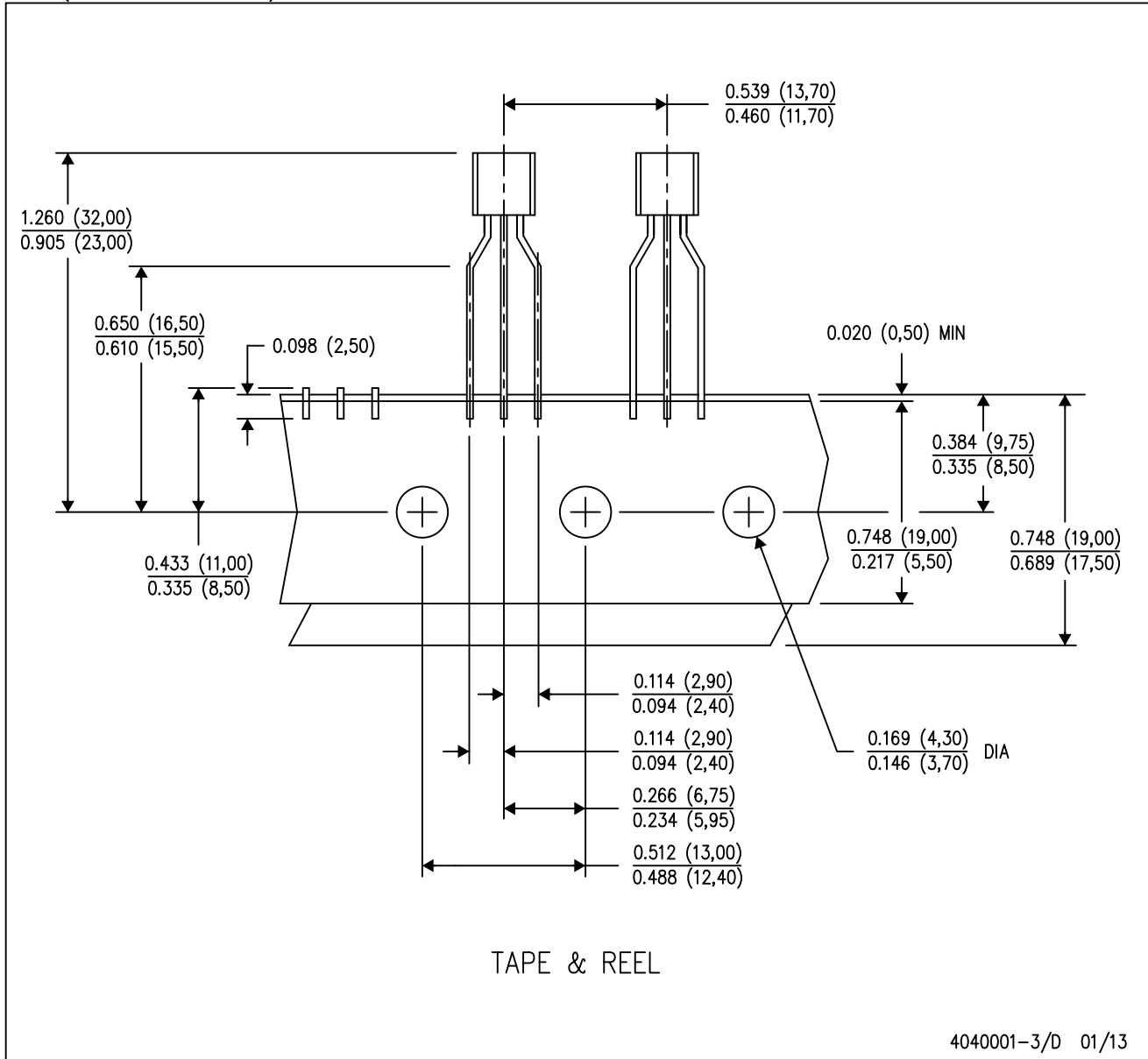
4040001-2/D 01/13

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Lead dimensions are not controlled within this area.
 - $\triangle D$ Falls within JEDEC TO-226 Variation AA (TO-226 replaces TO-92).
 - E. Shipping Method:
 - Straight lead option available in either bulk pack or tape & reel.
 - Formed lead option available in tape & reel or ammo pack.
 - Specific products can be offered in limited combinations of shipping mediums and lead options.
 - Consult product folder for more information on available options.

MECHANICAL DATA

LP (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Tape and Reel information for the Formed Lead Option package.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com